SN54LS540, SN54LS541, SN74LS540, SN74LS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SDLS180 - AUGUST 1979 - REVISED MARCH 1988

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- P-N-P Inputs Reduce D-C Loading
- Hysteresis at Inputs Improves Noise Margins
- Data Flow-thru Pinout (All Inputs on Opposite Side from Outputs)

description

These octal buffers and line drivers are designed to have the performance of the popular SN54LS240/SN74LS240 series and, at the same time, offer a pinout having the inputs and outputs on opposite sides of the package. This arrangement greatly enhances printed circuit board layout.

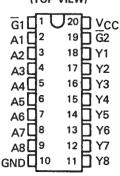
The three-state control gate is a 2-input NOR such that if either $\overline{G1}$ or $\overline{G2}$ are high, all eight outputs are in the high-impedance state.

The 'LS540 offers inverting data and the 'LS541 offers true data at the outputs.

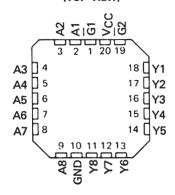
The SN54LS540 and SN54LS541 are characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LS540 and SN74LS541 are characterized for operation from 0° C to 70° C.

TYPE	RATED	RATED	TYPICAL	POWER
	[†] OL	¹он	DISSIP	ATION
	(SINK	(SOURCE	(ENAB	LED)
	CURRENT)	CURRENT)	'LS540	'LS541
SN54LS'	12 mA	- 12 mA	92.5 mW	120 mW
SN74LS'	24 mA	- 15 mA	92.5 mW	120 mW

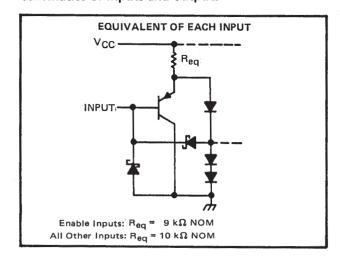
SN54LS540, SN54LS541 . . . J OR W PACKAGE SN74LS540, SN74LS541 . . . DW OR N PACKAGE (TOP VIEW)

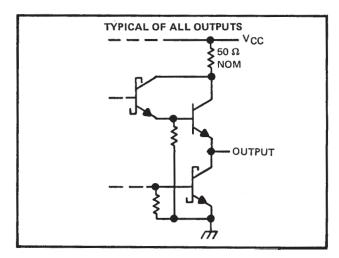


SN54LS540, SN54LS541 . . . FK PACKAGE (TOP VIEW)



schematics of inputs and outputs





PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

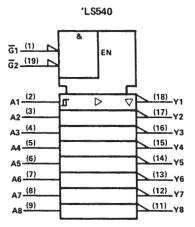


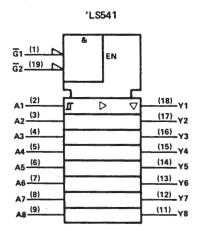
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SN54LS540, SN54LS541, SN74LS540, SN74LS541 **OCTAL BUFFERS AND LINE DRIVERS** WITH 3-STATE OUTPUTS

SDLS180 - AUGUST 1979 - REVISED MARCH 1988

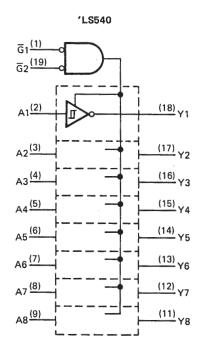
logic symbols†

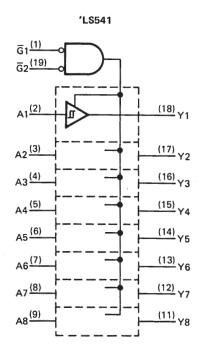




[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		
Input voltage		
Operating free-air temperature range	SN54LS540, SN54LS541	 – 55°C to 125°C
	SN74LS540, SN74LS541	 0°C to 70°C
Storage temperature range		 \dots 65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.



SN54LS540, SN54LS541, SN74LS540, SN74LS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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recommended operating conditions

DADAMETER		SN54LS	,		UNIT		
PARAMETER	MIN	NOM	MAX	MIN	NOM	MAX	ONT
Supply voltage, V _{CC} (see Note 1)	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-12			- 15	mA
Low-level output current, IOL			12			24	mA
Operating free-air temperature, TA	-55		125	0		70	°C

NOTE 1: Voltage values are with respect to network ground terminal.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED		TEGT CON	DITIONAT		SN54LS	,		SN74LS	,	LINUT	
	PARAMETER		TEST CON	DITIONS	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT	
VIH	High-level input volta	age			2			2			V	
VIL	Low-level input volta	ige					0.6			0.6	V	
VIK	Input clamp voltage		V _{CC} = MIN,	I _I = -18 mA			-1.5			- 1.5	V	
	Hysteresis (V _{T+} -	V _T _)	VCC = MIN		0.2	0.4		0.2	0.4		V	
Vон	High-level output vo	ltago	$V_{CC} = MIN,$ $V_{IL} = V_{IL} max,$	$V_{IH} = 2 V$, $I_{OH} = -3 \text{ mA}$	2.4	3.4		2.4	3.4		V	
VOH	riigii-ievei output vo	itage	$V_{CC} = MIN,$ $V_{IL} = 0.5 V,$	$V_{IH} = 2V,$ $I_{OH} = MAX$	2			2			•	
VOL	Low-level output vo	tage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V	
-02	Zott foroi ootpat voi		V _{IL} = V _{IL} max	I _{OL} = 24 mA					0.35	0.5	•	
lozh	Off-state output cur high-level voltage ap		V _{CC} = MAX,	V _O = 2.7 V			20			20	•	
lozL	Off-state output cur low-level voltage ap		V _{IH} = 2 V, V _{IL} = V _{IL} max	V _O = 0.4 V			- 20			- 20	μΑ	
11	Input current at max input voltage	kimum	V _{CC} = MAX,	V _I = 7 V			0.1			0.1	mA	
ΙН	High-level input curr	ent, any input	VCC = MAX,	V ₁ = 2.7 V			20			20	μΑ	
IIL	Low-level input curr	ent	V _{CC} = MAX,	V ₁ = 0.4 V			-0.2			-0.2	mA	
los	Short-circuit output	current §	V _{CC} = MAX		-40		- 225	-40		- 225	mA	
		Outputs high		'LS540		13	25		13	25		
		Outputs high]	'LS541		18	32		18	32		
loo	Supply current	Outputs low	V _{CC} = MAX,	'LS540		24	45		24	45	mA	
lcc	Supply culterit	Outputs low I	I Outputs low I	Outputs open	'LS541		30	52		30	52	'''^
		All outputs		'LS540		30	52		30	52		
		disabled		'LS541		32	55		32	55		

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

SN54LS540, SN54LS541, SN74LS540, SN74LS541 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS SDLS180 - AUGUST 1979 - REVISED MARCH 1988

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25 \,^{\circ}\text{C}$

	PARAMETER	TEST CO		'LS540		'LS541				
		1231 00	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
tPLH	Propagation delay time, low-to-high-level output				9	15		9	15	ns
tPHL	Propagation delay time, high-to-low-level output	$C_L = 45 pF$, See Note 2	$R_L = 667 \Omega$,		9	15		10	18	ns
tPZL	Output enable time to low level				25	38		25	38	ns
tPZH	Output enable time to high level				15	25		20	32	ns
tPLZ	Output disable time from low level	$C_L = 5 pF$,	$R_L = 667 \Omega$,		10	18		10	18	ns
^t PHZ	Output disable time from high level	See Note 2			15	25		18	29	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84155012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84155012A SNJ54LS 540FK	Samples
8415501RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415501RA SNJ54LS540J	Samples
8415501RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415501RA SNJ54LS540J	Samples
8415601SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415601SA SNJ54LS541W	Samples
8415601SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415601SA SNJ54LS541W	Samples
JM38510/32404B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32404B2A	Samples
JM38510/32404B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32404B2A	Samples
JM38510/32404BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32404BRA	Samples
JM38510/32404BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32404BRA	Samples
JM38510/32405BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32405BRA	Samples
JM38510/32405BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32405BRA	Samples
M38510/32404B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32404B2A	Samples
M38510/32404B2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32404B2A	Samples
M38510/32404BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32404BRA	Samples
M38510/32404BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32404BRA	Samples
M38510/32405BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32405BRA	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/32405BRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 32405BRA	Samples
SN54LS540J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS540J	Samples
SN54LS540J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS540J	Samples
SN54LS541J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS541J	Samples
SN54LS541J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS541J	Samples
SN74LS540DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samples
SN74LS540DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samples
SN74LS540DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samples
SN74LS540DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS540	Samples
SN74LS540N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS540N	Samples
SN74LS540N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS540N	Samples
SN74LS540NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS540	Samples
SN74LS540NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS540	Samples
SN74LS541DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Samples
SN74LS541DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Samples
SN74LS541DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Samples
SN74LS541DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS541	Samples
SN74LS541N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS541N	Samples
SN74LS541N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS541N	Samples
SN74LS541NE4	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS541N	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS541NE4	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS541N	Samples
SN74LS541NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS541	Samples
SN74LS541NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS541	Samples
SNJ54LS540FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84155012A SNJ54LS 540FK	Samples
SNJ54LS540FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	84155012A SNJ54LS 540FK	Samples
SNJ54LS540J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415501RA SNJ54LS540J	Samples
SNJ54LS540J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415501RA SNJ54LS540J	Samples
SNJ54LS541J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS541J	Samples
SNJ54LS541J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS541J	Samples
SNJ54LS541W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415601SA SNJ54LS541W	Samples
SNJ54LS541W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8415601SA SNJ54LS541W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

PACKAGE OPTION ADDENDUM

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- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS540, SN54LS541, SN74LS540, SN74LS541:

Catalog: SN74LS540, SN74LS541

Military: SN54LS540, SN54LS541

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS540DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LS540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS540NSR	so	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74LS541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74LS541NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1



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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS540DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74LS540DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS540NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74LS541DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74LS541NSR	so	NS	20	2000	367.0	367.0	45.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
84155012A	FK	LCCC	20	55	506.98	12.06	2030	NA
8415601SA	W	CFP	20	25	506.98	26.16	6220	NA
JM38510/32404B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/32404B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74LS540N	N	PDIP	20	20	506	13.97	11230	4.32
SN74LS541DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74LS541N	N	PDIP	20	20	506	13.97	11230	4.32
SN74LS541NE4	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54LS540FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS541W	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-150.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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